

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Yu-Rung Hsu</td><td>01/12/2011</td></tr><tr><td>Chen-Hua Yu</td><td>01/12/2011</td></tr><tr><td>Chao-Cheng Chen</td><td>01/12/2011</td></tr><tr><td>Ming-Huan Tsai</td><td>01/12/2011</td></tr><tr><td>Hsien-Hsin Lin</td><td>01/12/2011</td></tr><tr><td>Hsueh-Chang Sung</td><td>01/12/2011</td></tr></tbody></table>		Name	Execution Date	Yu-Rung Hsu	01/12/2011	Chen-Hua Yu	01/12/2011	Chao-Cheng Chen	01/12/2011	Ming-Huan Tsai	01/12/2011	Hsien-Hsin Lin	01/12/2011	Hsueh-Chang Sung	01/12/2011
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Ming-Huan Tsai	01/12/2011														
Hsien-Hsin Lin	01/12/2011														
Hsueh-Chang Sung	01/12/2011														
RECEIVING PARTY DATA															
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.														
Street Address:	No. 8, Li-Hsin Rd 6														
Internal Address:	Science-Based Industrial Park														
City:	Hsin-Chu														
State/Country:	TAIWAN														
Postal Code:	300-77														
PROPERTY NUMBERS Total: 1															
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>12645834</td></tr></tbody></table>		Property Type	Number	Application Number:	12645834										
Property Type	Number														
Application Number:	12645834														
CORRESPONDENCE DATA															
Fax Number:	(214)200-0853														
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ATTORNEY DOCKET NUMBER:	2009-0352/24061.1326														

OP \$40.00 12645834

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PATENT
REEL: 026540 FRAME: 0633

NAME OF SUBMITTER:

David M. O'Dell

Total Attachments: 3

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ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|------------------|----|------------------------------------------------------------------------------------|
| (1) | Yu-Rung Hsu | of | 7F-1, No. 2, Lane 12, Daxue Road, East District
Tainan City 701, Taiwan, R.O.C. |
| (2) | Chen-Hua Yu | of | No. 3, 38 Waterfront Road 2
Hsin-Chu, Taiwan, R.O.C. |
| (3) | Chao-Cheng Chen | of | #46 3F-2, Lui-Sui Road
Shin-Chu City, Taiwan, R.O.C. |
| (4) | Ming-Huan Tsai | of | 8F., No.41, Guangming 6th Rd., Zhubei City,
Hsinchu County, Taiwan (R.O.C.) |
| (4) | Hsien-Hsin Lin | of | 11F-2, No. 21, 23 Lane, Guan-Dong Rd.
Hsinchu City, Taiwan (R.O.C.) |
| (6) | Hsueh-Chang Sung | of | 3F., No.208, Wencai St., Zhubei City,
Hsinchu County 302, Taiwan (R.O.C.) |

have invented certain improvements in

**METHOD OF FABRICATING STRAINED STRUCTURE
IN SEMICONDUCTOR DEVICE**

for which we filed an application for Letters Patent of the United States of America on December 23, 2009, as U.S. Serial No. 12/645,834; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

Docket No.: 2009-0352 / 24061.1326
Customer No.: 42717

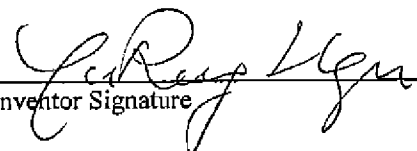
AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Yu-Rung Hsu

Residence Address: 7F-1, No. 2, Lane 12, Daxue Road, East District
Tainan City 701, Taiwan, R.O.C.

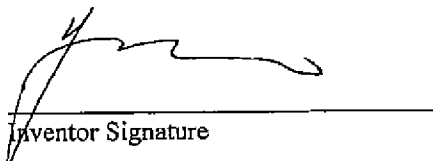
Dated: Jan 12, 2011


Inventor Signature

Inventor Name: Chen-Hua Yu

Residence Address: No. 3, 38 Waterfront Road 2
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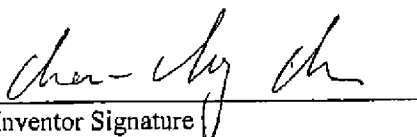
Dated: 1/12/11


Inventor Signature

Inventor Name: Chao-Cheng Chen

Residence Address: #46 3F-2, Lui-Sui Road
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Dated: 1/12, 2011


Inventor Signature

Docket No.: 2009-0352 / 24061.1326

Customer No.: 42717

Inventor Name: Ming-Huan Tsai

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Ming Huan Tsai

Dated: 1/12 2011

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Inventor Name: Hsien-Hsin Lin

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Dated: 1/12 2011

Hsueh - Chang Sung

Inventor Signature